

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "DMD_P3P3V" represents connection to the +3.3V digital power plane.
2. The symbol  represents connection to the digital ground plane.
3. A "Z" suffix on a signal name indicates an active low signal.
4. All components with designators "U", "D", "Y" and "Q" are electrostatic discharge sensitive.
5. All resistor values are in ohms, 1/16W and 5% unless otherwise specified.

COMPUTER GENERATED DRAWING. DO NOT REVISE MANUALLY

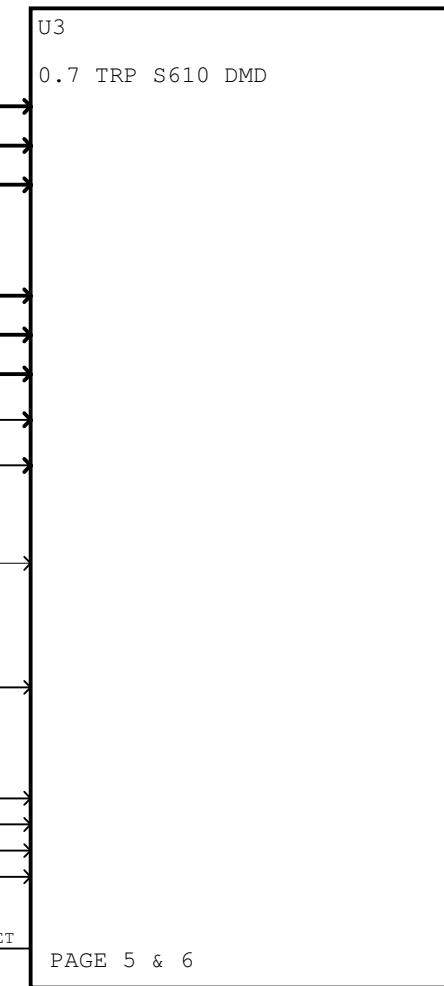
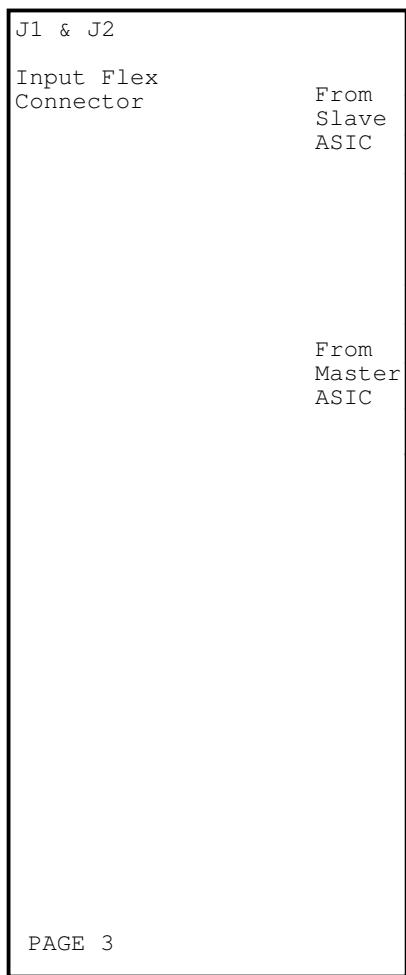
REVISONS

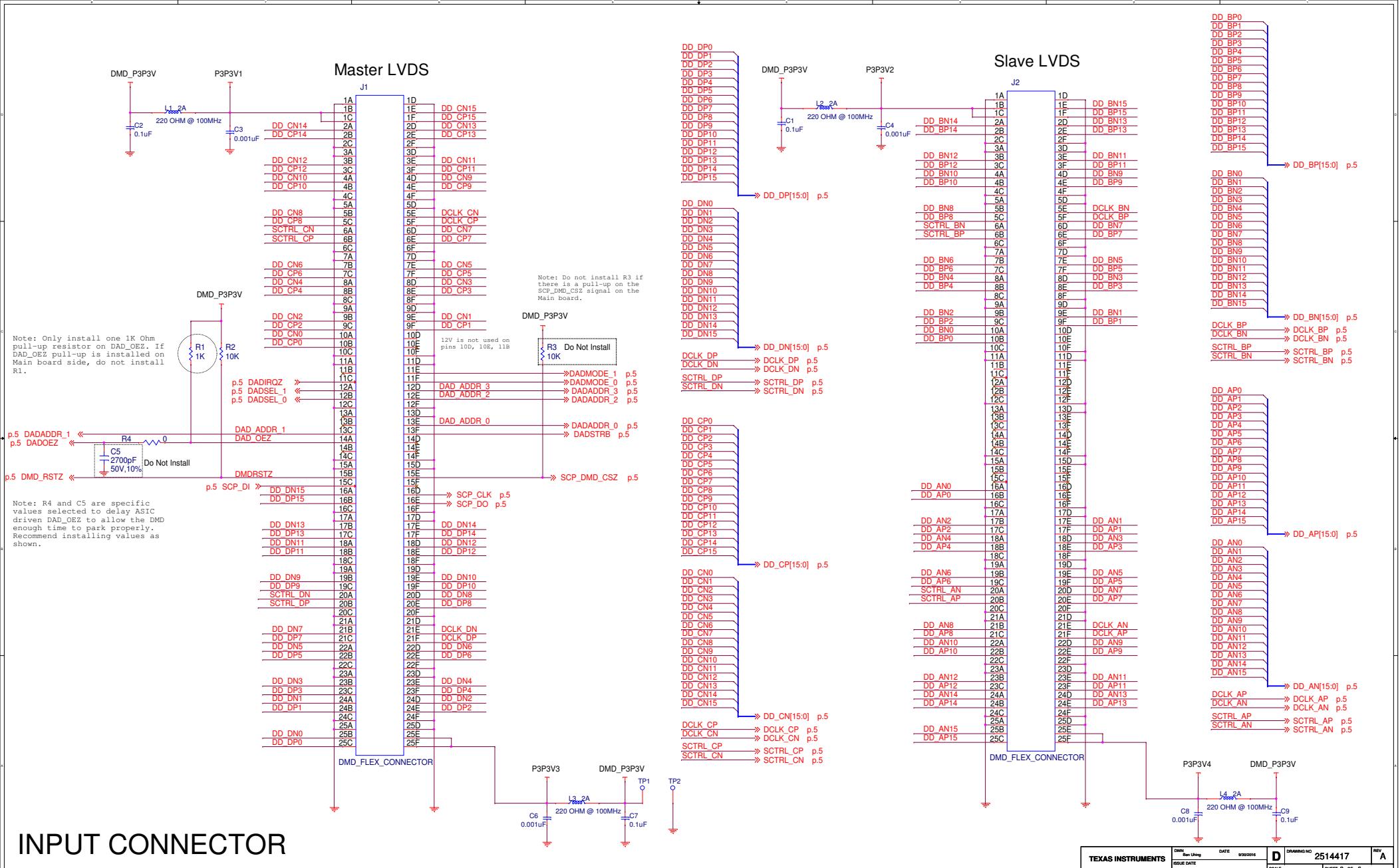
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2148113: Initial Release	03/10/2015	DH

HIGHEST REFERENCE DESIGNATORS USED

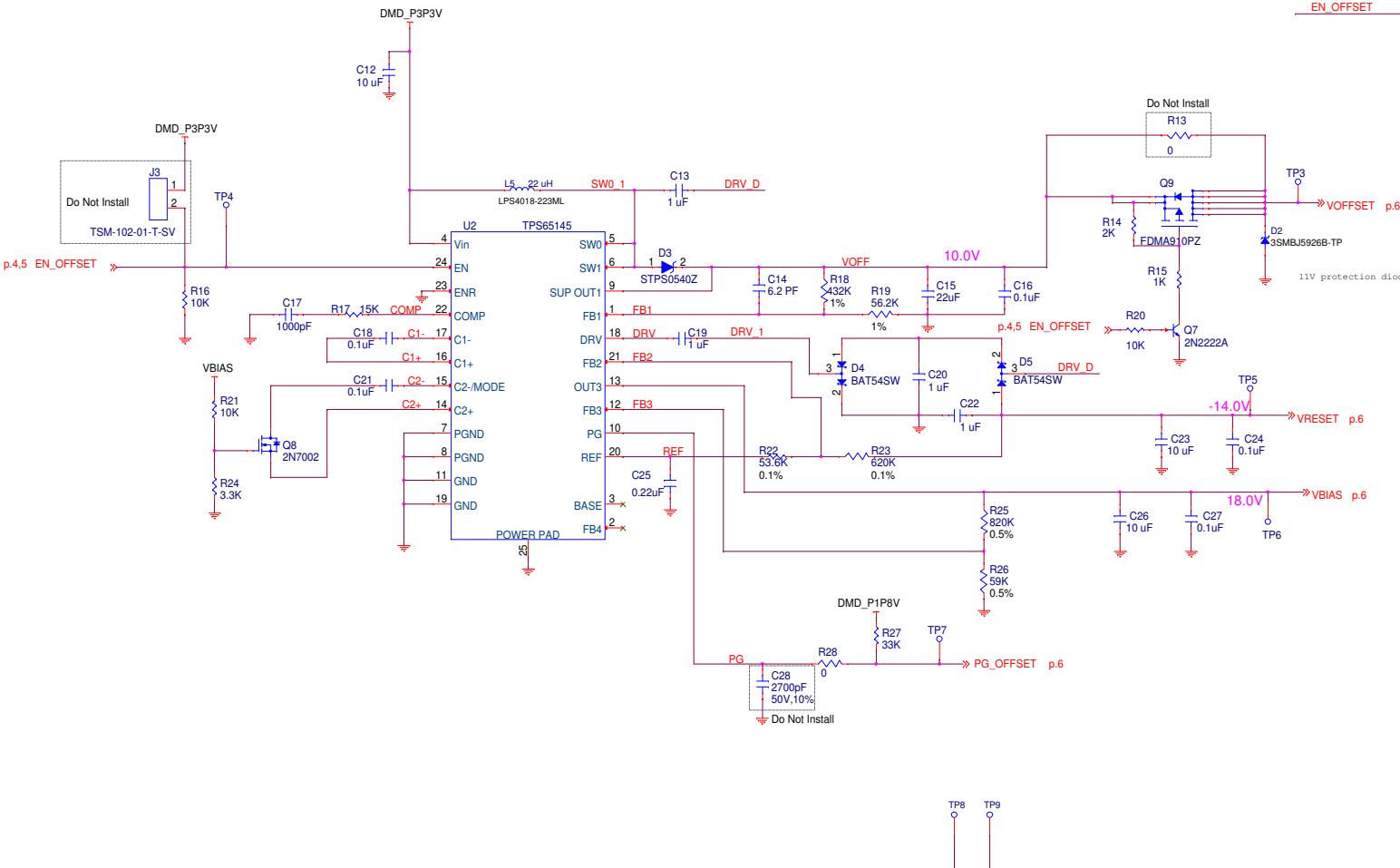
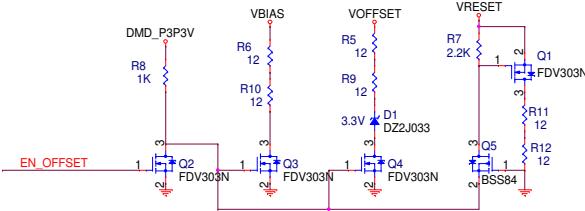
C103	D5	J4	L5	R56	TP31	U7
Q9						

DNN	Ben Uhing	DATE	9/30/2016	TEXAS INSTRUMENTS <small>(C) COPYRIGHT 2015 TEXAS INSTRUMENTS ALL RIGHTS RESERVED</small>
ENGR	Amy White	3/9/2015		
APVD				
MPG				
2514418	0314SS	QA		TITLE TIDA-01347 P66 4KUHD DMD Board
NEXT ASSY	USED ON			
APPLICATION	SW	Cadence 16.6		
D	DRAWING NO	2514417	REV	
	SCALE		A	
	SHEET	1	of	8



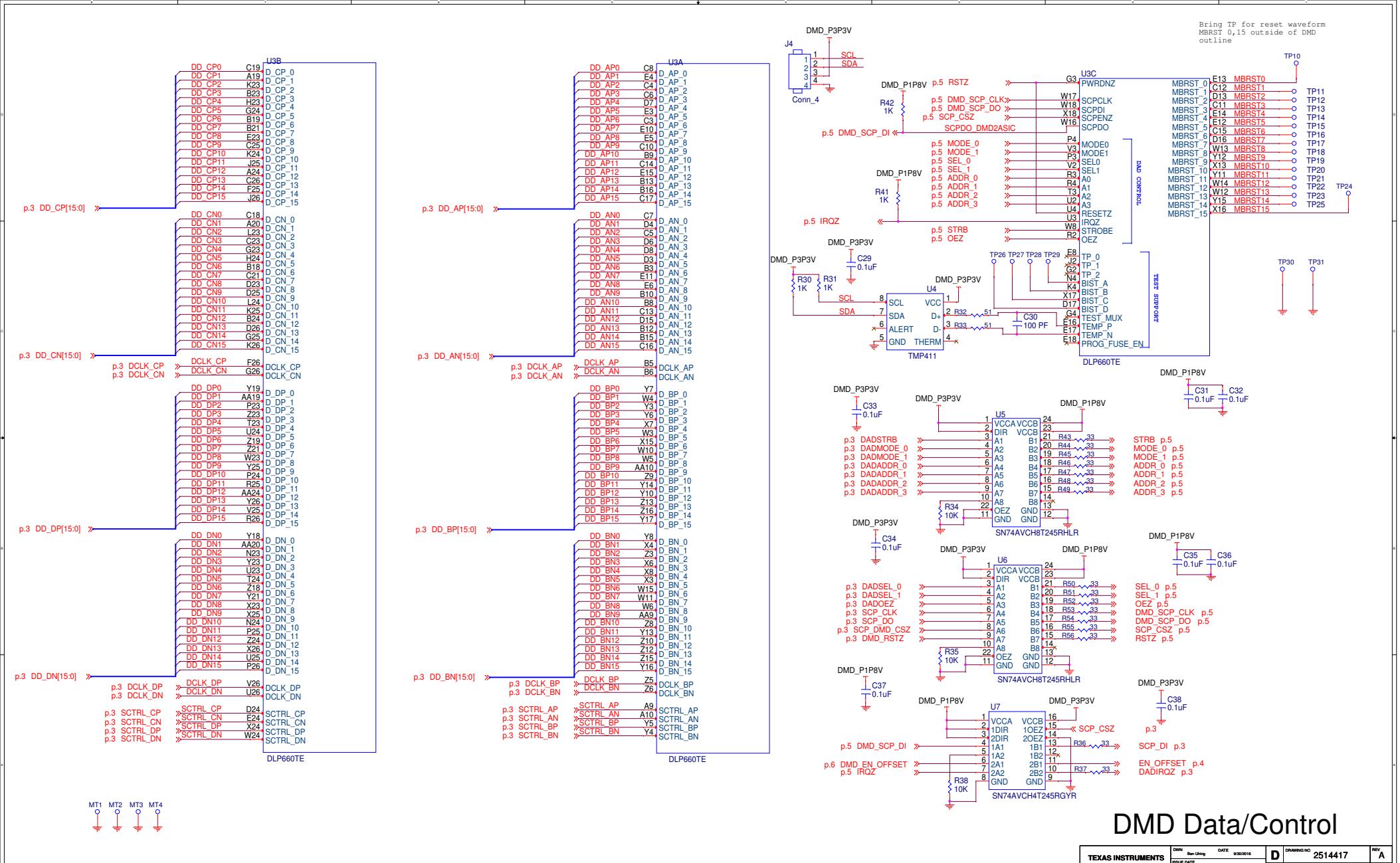


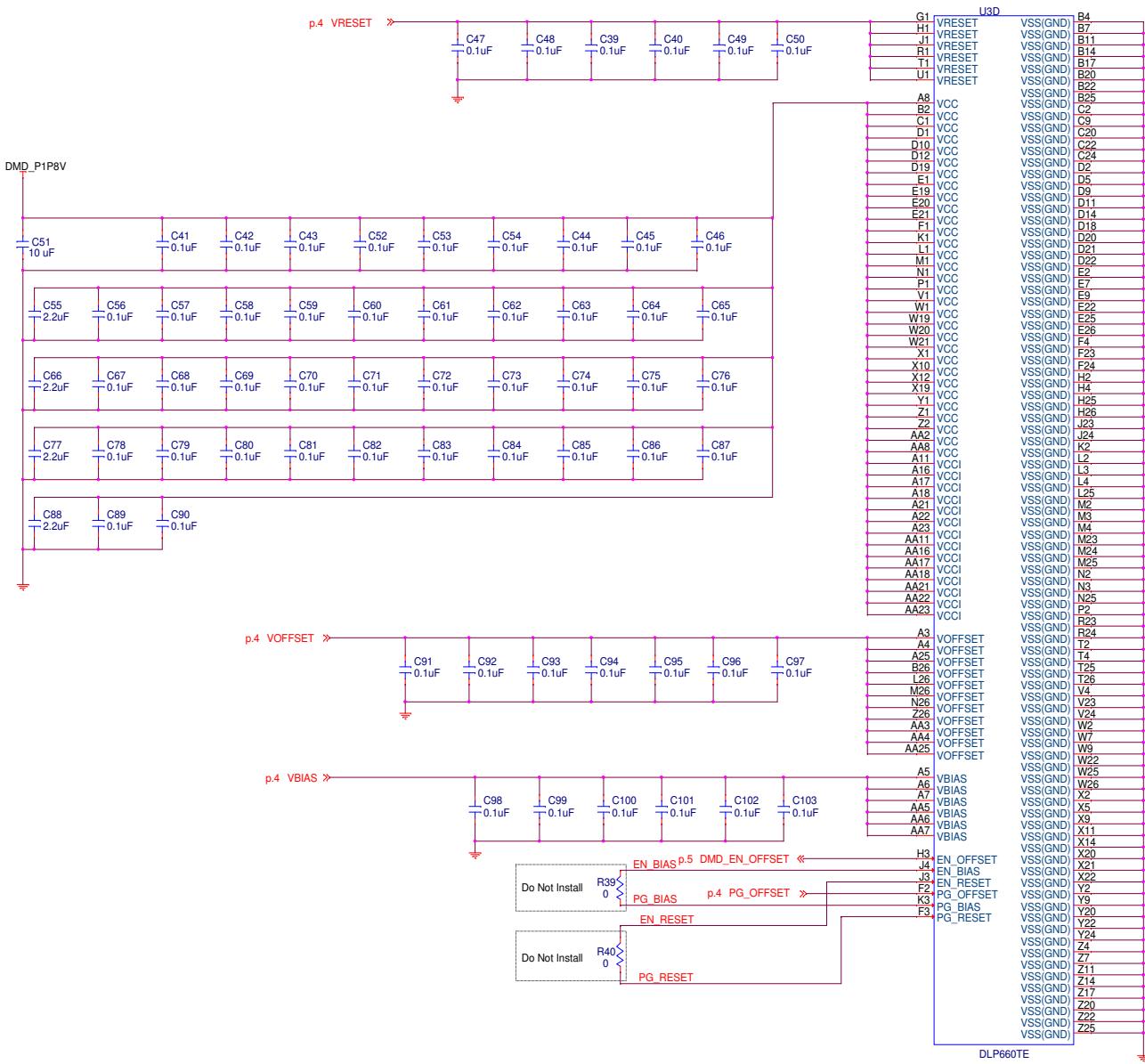
Power Down Circuitry



DMD Power Supplies

TEXAS INSTRUMENTS	DRW Ben Liang	DATE 05/02/2016	D DRAWING NO 2514417	REV A
	ISSUE DATE		SCALE	HEET 4 OF 6





DMD Power/Gnd

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